

The method relates to radio electronics, in particular to method for manufacturing thermally conductive printed circuit boards with temperature compensation subjected to influence of thermal, impact and vibration loads. The method for manufacturing a thermally conductive printed circuit board comprises making thereof structure by sequential location of at least on one side of a metallic basis correspondingly a first adhesive, flexible material, a second adhesive and a printed circuit board with previously formed conductors pattern on the said board thereupon, afterwards the obtained elements of the structure are connected to one another under influence of temperature and pressure. The pattern is formed at least on a two-layer printed circuit board and than, a metal layer is deposited on formed commutating conductors of the pattern, on side of metallic basis, which has the Brinell hardness number of $15 \div 100$ kPa over the range of $+90 \div +190$ °C. As an adhesive located between flexible material and the printed circuit board, material having Brinell hardness number ≤ 15 over the range of $+90 \div +190$ °C is used. Hardness of metal deposited on commutating conductors of pattern is greater than hardness of the adhesive located between flexible material and the printed circuit board, and less than flexible material hardness at temperature of $+90 \div +190$ °C. Total thickness of adhesives and located between flexible material is greater than or equal to a height of commutating conductors together with metal having low hardness deposited on said conductors. The invention allows widening scope of application and operation capability, increasing output of applicable printed circuit boards and decreasing manufacturing cost.